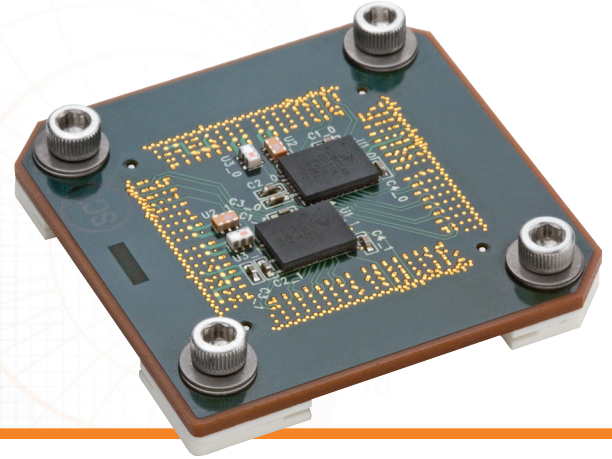


PyramidAccel

Wafer-less Debug Fixture for Rapid Test Program Development



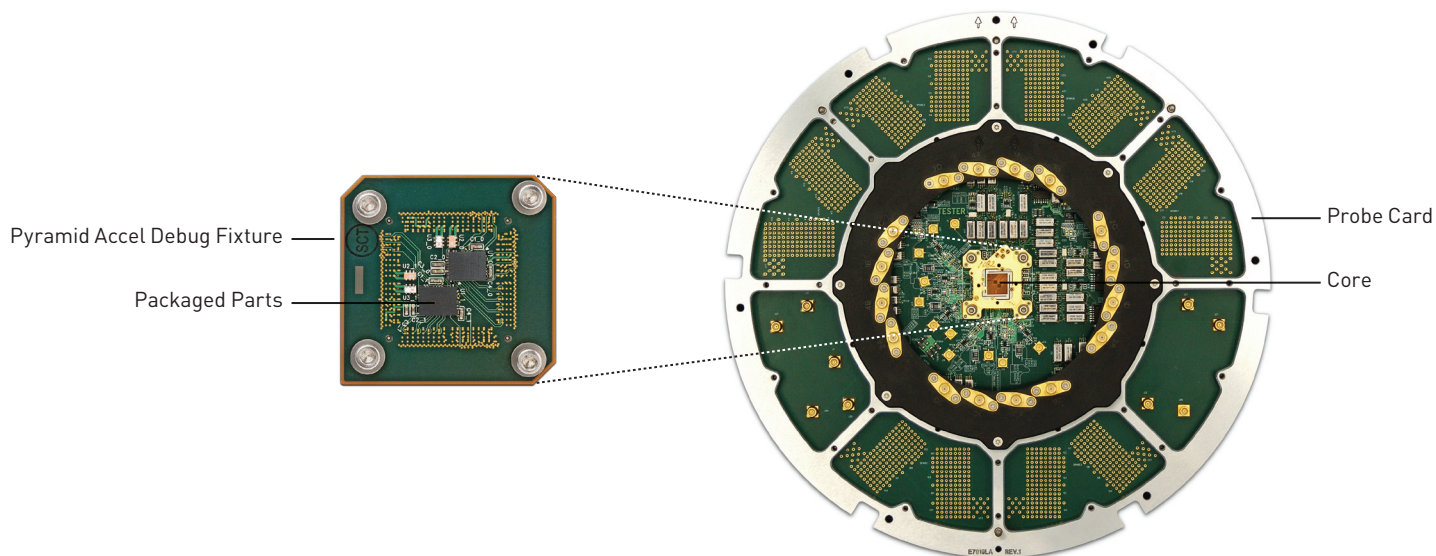
DATA SHEET

Cascade Microtech's Pyramid Accel™ debug fixture provides a unique and innovative approach for accelerating the development of test programs for System-on-Chip (SoC) and RF devices by up to 30%. Comprised of a PCB containing customer-supplied packaged parts mounted on an Advanced Spring Interposer, the Pyramid Accel fixture is mounted directly on the Pyramid Probe® card to enable necessary debugging for "Known-Good Test Program" status before silicon wafers are ready for production test. This approach facilitates more predictability by reducing the variables during test program debug. By eliminating the need for a wafer prober during test program debug, Pyramid Accel lowers your cost of test, while streamlining the entire development process. Once production test has begun, the Pyramid Accel fixture delivers the added benefit of providing a "golden reference" to allow fast diagnosis of test program issues that arise, resulting in less production downtime.

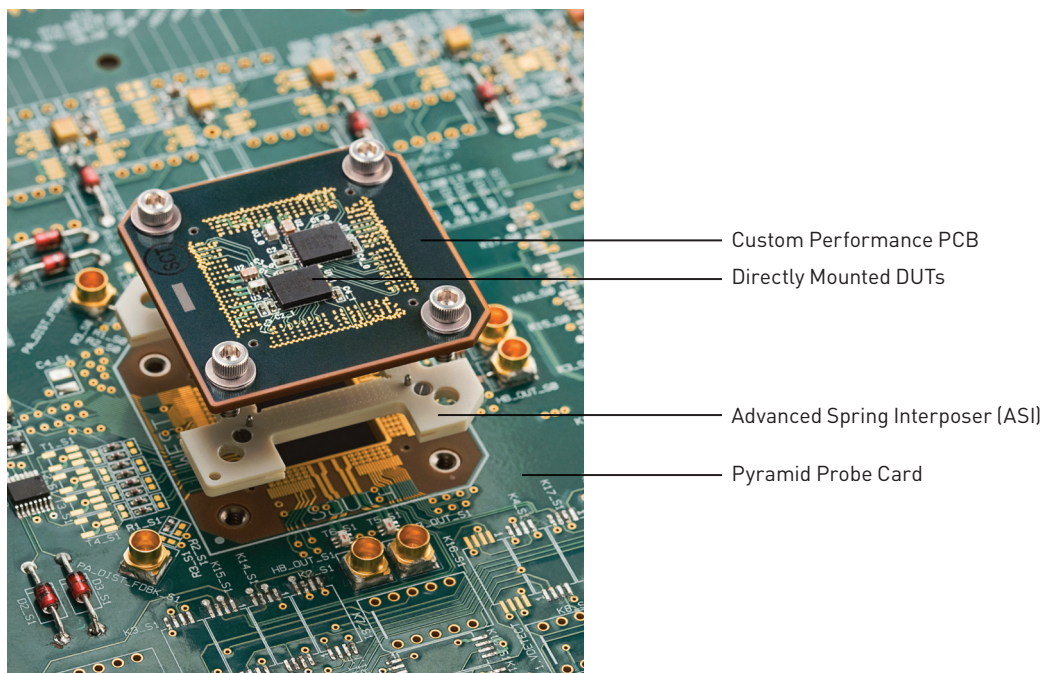
FEATURES / BENEFITS

Superior signal performance	Microstrip and stripline options provide excellent signal integrity, all the way to the package DUT pin. With a single probe card solution, performance with bare wafer device and a packaged device can be compared.
Mechanical robustness	During production test, the Pyramid Accel fixture provides a golden reference, allowing quick isolation of probe card or test equipment issues. Low maintenance and permanent probe tip placement improve test cell uptime, reducing the cost of ownership compared to other probing technologies.
Versatile and cost-effective	With the Grypper™ socket option, Cascade Microtech's unique solder down device footprint, BGA test sockets can be directly mounted on the Pyramid Accel PCB without socket mounting holes or hardware considerations, eliminating the need for a special test socket footprint. Available for all Pyramid Probe cores, Pyramid Accel can be used with all device types. Advanced Spring Interposer (ASI) is designed for fast replacement of interconnect elements.

PYRAMID ACCEL CONCEPT



PYRAMID ACCEL ASSEMBLY



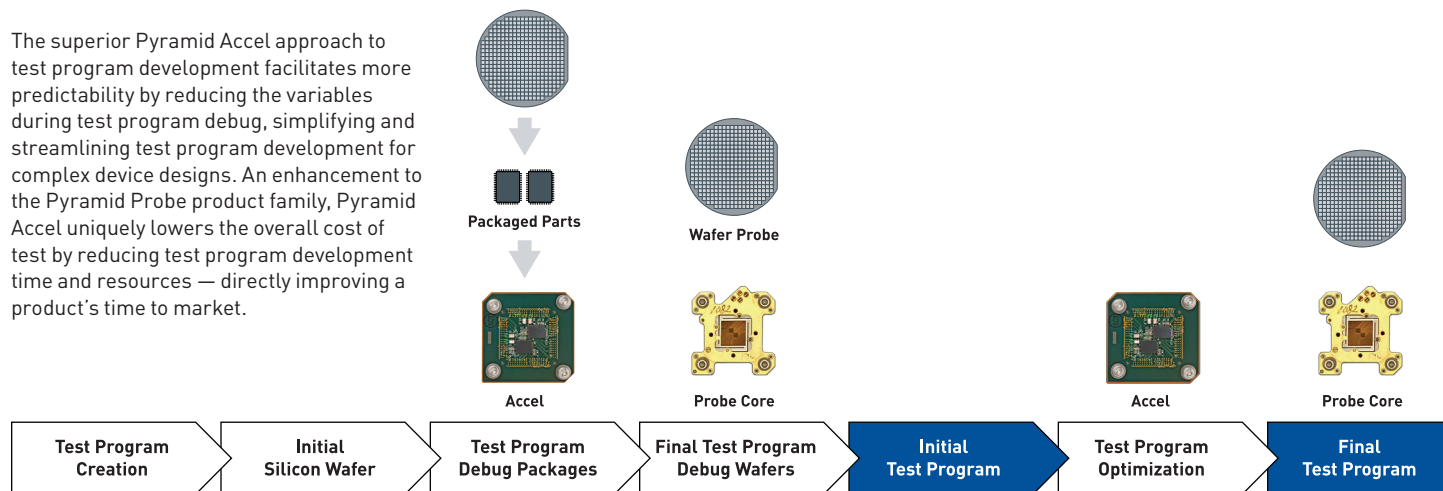
GRYPHER SOCKET OPTION

As an option to directly mounting the DUTs on the Pyramid Accel fixture, you can also use Cascade Microtech's innovative BGA Grypper solder down device footprint BGA test sockets. Featuring a 0.4 mm – 1.0 mm pitch and outstanding signal integrity, Grypper test sockets can be directly mounted on the Pyramid Accel PCB without socket mounting holes or hardware considerations, eliminating the need for a special test socket footprint.



PYRAMID ACCEL TEST PROGRAM PROCESS

The superior Pyramid Accel approach to test program development facilitates more predictability by reducing the variables during test program debug, simplifying and streamlining test program development for complex device designs. An enhancement to the Pyramid Probe product family, Pyramid Accel uniquely lowers the overall cost of test by reducing test program development time and resources — directly improving a product's time to market.



ELECTRICAL

Trace options	Microstrip, Stripline, Power, Ground, DC
Maximum current/signal	0.5 A
Max power 50 Ω microstrip	+33 dBm CW, +36 dBm pulsed
Max power 50 Ω Coplanar Waveguide (CPW)	+33 dBm CW, +39 dBm pulsed

POWER SUPPLY TRACE PERFORMANCE

Power trace impedance	10 Ω
Max current std. power trace (limited by probe)	0.5 A
Max current per power supply	10 A

SIGNAL TRACE PERFORMANCE

STANDARD

Signal line impedance	50 Ω nominal
Return loss (S_{11}) to coax	>10 dB @ 10 GHz

OPTIONAL

Differential impedance	50 Ω , 100 Ω and 200 Ω
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SIGNAL TRACE LENGTH MATCHING

Typical signal	no match
Optimized signal (custom layout)	± 1.5 ps (3 ps window)

SERIES PATH RESISTANCE (SPR)

Accel	A100	A300	A400	A500	A800
Microstrip, Stripline	1.2 Ω	1.2 Ω	2 Ω	3 Ω	3 Ω

RF-CLASS BANDWIDTH AND RISE TIME PERFORMANCE

TRANSMISSION LINE			BANDWIDTH AND RISE TIME	
Accel PCB	Probe card PCB	Probe card connector	Pyramid Accel	
Microstrip	Microstrip	Pogo pad	2 GHz	200 ps
Microstrip	Microstrip	PCB coaxial	7 GHz	50 ps

OPTIONAL COMPONENTS ATTACHED TO ACCEL PCB

Package type	SMT
Sizes	0201, 0402 (preferred), 0603, 0805

ADVANCED SPRING IMPOSER: MECHANICAL

Probe contact life	1000 insertions minimum
Max operating temperature	125°C

ADVANCED SPRING IMPOSER: ELECTRICAL

Plastic dielectric strength	540 V/mil.
Plastic volume resistivity	1 E+15 Ωcm
Plastic dielectric constant (1 MHz)	3
Probe resistance	50 mΩ
Probe inductance	2.5 nH @ 6 GHz
Probe bandwidth (-0.20dB)	6 GHz

ADVANCED SPRING IMPOSER: CHEMICAL

Water absorption immersion (24 hr)	0.01%
Alcohol (isopropanol, methanol only)	Acceptable service
UV or sunlight exposure	Discoloration may occur

ACCEL OPTIONS

Previous frame core name	RFC	SRF	MSI	LSI	VLSR
Pyramid Probe core name	P100	P300	P400	P500	P800
Pyramid Accel name	A100	A300	A400	A500	A800
I/O capacity	108	264	408	520	804

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Data subject to change without notice

Cascade Microtech, Inc.
Corporate Headquarters
toll free: +1-800-550-3279
phone: +1-503-601-1000
email: cmi_sales@cmicro.com

Germany
phone: +49-89-9090195-0
email: cmg_sales@cmicro.com

Japan
phone: +81-3-5615-5150
email: cmj_sales@cmicro.com

China
phone: +86-21-3330-3188
email: cmc_sales@cmicro.com

Singapore
phone: +65-6873-7482
email: cms_sales@cmicro.com

Taiwan
phone: +886-3-5722810
email: cmt_sales@cmicro.com

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www.cascademicrotech.com

